

United States Patent and Trademark Office

UNITED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Office Address: COMMISSIONER FOR PATENTS P.O. Box 1450 Alexandria, Virginia 22313-1450 www.uspto.gov

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/814,855	03/30/2004	Hannu Ventomaki	915-007.083	5601
4955	7590 02/09/2006		EXAMINER	
WARE FR	ESSOLA VAN DER SI	NGUYEN, JIMMY		
ADOLPHS(ON, LLP			
BRADFORD GREEN BUILDING 5			ART UNIT	PAPER NUMBER
755 MAIN STREET, P O BOX 224			2829	
MONROE, CT 06468			DATE MAILED: 02/09/2006	

Please find below and/or attached an Office communication concerning this application or proceeding.

•						
	Application No.	Applicant(s)				
	10/814,855	VENTOMAKI, HANNU				
Office Action Summary	Examiner	Art Unit				
	Jimmy Nguyen	2829				
The MAILING DATE of this communication app Period for Reply	pears on the cover sheet with the c	correspondence address				
A SHORTENED STATUTORY PERIOD FOR REPL' THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.1 after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a repl If NO period for reply is specified above, the maximum statutory period of Failure to reply within the set or extended period for reply will, by statute Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	36(a). In no event, however, may a reply be tin y within the statutory minimum of thirty (30) day will apply and will expire SIX (6) MONTHS from , cause the application to become ABANDONE	nely filed s will be considered timely. the mailing date of this communication. D (35 U.S.C. § 133).				
Status						
1) Responsive to communication(s) filed on 13 Ju	une 2005.					
	· · · · · · · · · · · · · · · · · · ·					
3) Since this application is in condition for allowa						
Disposition of Claims						
4) Claim(s) 1-5, 7 - 29 is/are pending in the application Papers 4a) Of the above claim(s) is/are withdray 5) Claim(s) is/are allowed. 6) Claim(s) 1-5, 7 - 29 is/are rejected. 7) Claim(s) is/are objected to. 8) Claim(s) are subject to restriction and/or Application Papers 9) The specification is objected to by the Examine	wn from consideration. r election requirement.					
10) ☐ The drawing(s) filed on is/are: a) ☐ acc						
Applicant may not request that any objection to the						
Replacement drawing sheet(s) including the correct 11) The oath or declaration is objected to by the Ex						
Priority under 35 U.S.C. § 119						
12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of: 1. Certified copies of the priority document 2. Certified copies of the priority document 3. Copies of the certified copies of the priority application from the International Bureau * See the attached detailed Office action for a list	s have been received. s have been received in Applicati rity documents have been receive u (PCT Rule 17.2(a)).	on No ed in this National Stage				
Attachment(s) 1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)						
Paper No(s)/Mail Date	6)					

DETAILED ACTION

Response to Argument

The amendment filed 11/23/05 has been carefully considered with the following effect:

a. Applicant's arguments with respect to claims 1, 13 have been considered but are most in view of the new ground(s) of rejection.

Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

2. Claims 1 - 5, 7 - 29 are rejected under 35 U.S.C. 102(e) as being anticipated by Barr et al. (US 2004/0257090)

As to claim 1, Barr et al disclose (figs 1, 2, 6) a method for analyzing connection conditions between an integrated circuit package (daughter board, column 1 paragraph 20) and a circuit board (mother board, column 1 paragraph 20) comprising step of

Application/Control Number: 10/814,855

Art Unit: 2829

electrically coupling said integrated circuit package (daughter board, column 1 paragraph 20) to said circuit board (mother board, column 1 paragraph 20) by coupling elements (102),

mechanically connecting IC (daughter board) with said circuit board (mother board) by support elements (pins 1 and 2 of daughter board, fig 2)

electrically connecting (fig 2) at least two of support elements (pins 1, 2) with each other on the side of IC package

picking off physical values (fig 6, by 104) to determine mechanical properties if support

concluding (by 104) a condition of electrical coupling of IC package with circuit board from determined mechanical properties of support element.

As to claim 2, Barr et al disclose (figs 1, 2, 6) the electrical values (by 104 column 2 paragraph 24) are pick off from support elements (pins 1, 2).

As to claim 3, Barr et al disclose (figs 1, 2, 6) the electrical current (by 104 column 2 paragraph 24) within the support element (pins 1, 2) is picked off.

As to claims 4, 5, Barr et al disclose (figs 1, 2, 6) the mechanical values (the joint solder are making sure the pins are connected) are picked off from support elements (pins 1, 2) by using the strain gauge (transmission lines).

Application/Control Number: 10/814,855

Art Unit: 2829

As to claim 7, Barr et al disclose (figs 1, 2, 6) the connection condition is determined in intervals (paragraph 22).

As to claims 8 - 12, 22, 24 - 26, Barr et al disclose (figs 1, 2, 6) determined connection condition is determined, store and presented on a user interface (106), a error message is generated (to the system management).

As to claims 13, 27, Barr et al disclose (figs 1, 2, 6) a system for analyzing connection conditions between an integrated circuit package (daughter board) and a circuit board (motherboard) comprising:

coupling elements (102) coupling said integrated circuit package (daughter board) electrically to said circuit board (motherboard), and

support elements (pins 1, 2) connecting said integrated circuit package (daughter board) mechanically with said circuit board (motherboard), wherein the system further comprising:

means electrically connecting at least two support elements (pins 1, 2) with each other on the side of the IC package (fig 2)

measuring (by 104) means arranged at said support elements (pins 1, 2) for picking -off physical values between said support elements, and

evaluation (by 104) means for evaluating said physical values to determine mechanical properties of support elements (pins 1, 2), and for concluding a condition of

Page 5

Application/Control Number: 10/814,855

Art Unit: 2829

electrical coupling of IC package with circuit board (determining the continuity) from determined mechanical properties of support elements

As to claim 14, Barr et al disclose (figs 1, 2, 6) the support elements (pins 1, 2) are arranged between circuit board (mother board) and IC package (daughter board).

As to claim 15, Barr et al disclose (figs 1, 2, 6) the support elements (pins 1, 2) are solder pads elements (or pins)

As to claim 16, Barr et al disclose (figs 1, 2, 6) the support elements (pins 1, 2) are arranged adjacent to coupling elements (102).

As to claim 17, Barr et al disclose (figs 1, 2, 6) the support elements (pins 1, 2) are arranged semicircular along coupling elements (102).

As to claim 18, Barr et al disclose (figs 1, 2, 6) the support elements (pins 1, 2) are arranged along edges and or at corners of IC package (daughter board).

As to claim 19, Barr et al disclose (figs 1, 2, 6) IC package (daughter board) is a CSP of chip (paragraph 20).

Application/Control Number: 10/814,855 Page 6

Art Unit: 2829

As to claims 20, 21, Barr et al disclose (figs 1, 2, 6) the means of measuring electrical and mechanical condition of support element (pins 1, 2).

As to claim 23, Barr et al disclose (figs 1, 2, 6) the evaluation means compare picked off physical values with comparative values to determine the connection condition (voltage level, paragraph 22)

As to claims 28, 29, Barr et al disclose (figs 1, 2, 6) the computer program and product system (302) to cause a processor to analyze connection conditions between the IC package and a circuit board.

Conclusion

3. Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any

Application/Control Number: 10/814,855

Art Unit: 2829

extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Jimmy Nguyen whose telephone number is 571 – 272-1965. The examiner can normally be reached on Monday - Friday from 9am to 5pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Ramiz Nestor, can be reached on 571-272-2034. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Jimmy Nguyen

JN. Jan 26, 2006 VINH NGUYEN ' PRIMARY EXAMINER

Page 7

A.4. 2829

02/01/06